

Interface roughness improves stretchable electronics reliability

Citation for published version (APA):

Neggers, J., Hoefnagels, J. P. M., & Geers, M. G. D. (2012). *Interface roughness improves stretchable electronics reliability*. Poster session presented at Mate Poster Award 2012 : 17th Annual Poster Contest.

Document status and date:

Published: 01/01/2012

Document Version:

Accepted manuscript including changes made at the peer-review stage

Please check the document version of this publication:

- A submitted manuscript is the version of the article upon submission and before peer-review. There can be important differences between the submitted version and the official published version of record. People interested in the research are advised to contact the author for the final version of the publication, or visit the DOI to the publisher's website.
- The final author version and the galley proof are versions of the publication after peer review.
- The final published version features the final layout of the paper including the volume, issue and page numbers.

[Link to publication](#)

General rights

Copyright and moral rights for the publications made accessible in the public portal are retained by the authors and/or other copyright owners and it is a condition of accessing publications that users recognise and abide by the legal requirements associated with these rights.

- Users may download and print one copy of any publication from the public portal for the purpose of private study or research.
- You may not further distribute the material or use it for any profit-making activity or commercial gain
- You may freely distribute the URL identifying the publication in the public portal.

If the publication is distributed under the terms of Article 25fa of the Dutch Copyright Act, indicated by the "Taverne" license above, please follow below link for the End User Agreement:

www.tue.nl/taverne

Take down policy

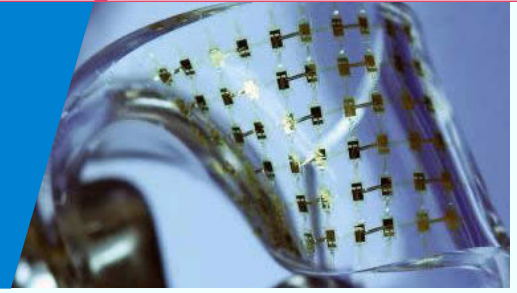
If you believe that this document breaches copyright please contact us at:

openaccess@tue.nl

providing details and we will investigate your claim.

Interface roughness improves stretchable electronics reliability

Jan Neggers, Johan Hoefnagels and Marc Geers



Introduction

Stretchable electronic devices enable a range of futuristic bio-compatible applications (Fig. 1-2). The designs of these devices usually consist of off-the-shelf electronic components, interconnected with metal lines made stretchable by design, (Fig. 3a) embedded in a stretchable (rubber) matrix material.

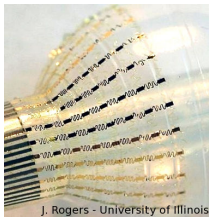


Figure 1: Hart ablation catheter

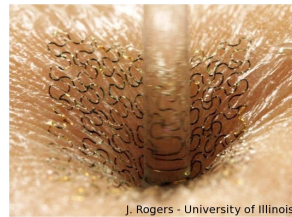


Figure 2: Smart skin

Many design solutions can be found in literature, one of which is the horseshoe shape interconnect. However, interface delamination is a common precursor to failure in all designs (Fig. 3c).

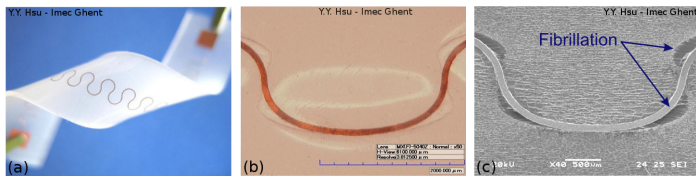


Figure 3: (a) Horseshoe shaped interconnect sample, (b) uni-axially stretched under a microscope, (c) showing fibrillation at the interface failure position, when imaging in-situ in an ESEM.

Goal

Understanding the delamination micro-mechanics responsible for the interface toughness. This knowledge can be applied to all interconnect designs to increase their stretchability.

Experiments

Four types of peel-test experiments are performed to investigate the characteristics of interfaces, i.e., two types of roughness in two opening modes. Moreover, the delamination front is visualized with in-situ ESEM imaging.

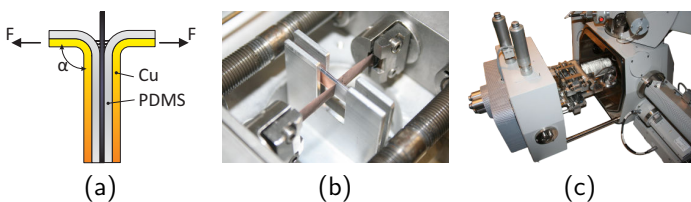


Figure 4: (a) Schematic of a 90° peel-test (b) 90° peel-test sample mounted in a tensile-stage, (c) which is mounted in the ESEM,

Figure 5 shows that the roughness morphology dictates the shape of the fibrils. Moreover, the interface of the rougher sample is

more tough, this is due to the extra energy dissipation in the longer fibrils.

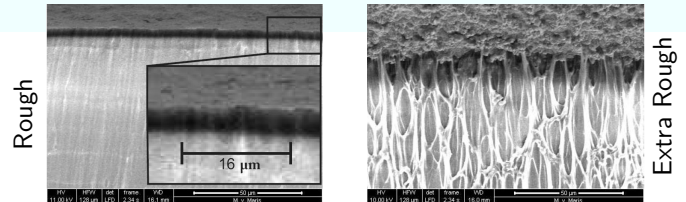


Figure 5: in-situ visualisation of the delamination micro-mechanics, i.e. the forming, stretching and ultimately rupture of fibrils.

Figure 6 shows that the area fraction of rubber left behind on the new metal surface is greater for the rougher sample indicating an increase in rubber fracture, again showing that the rougher sample is more tough.

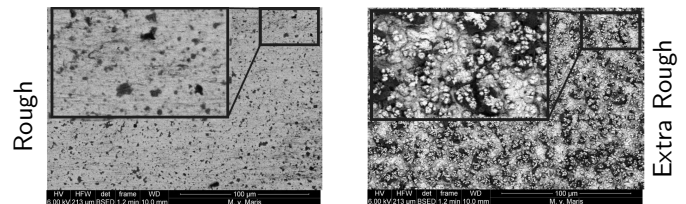


Figure 6: The new metal surfaces for both roughness types, for a 90° peel test, i.e. crack opening mode.

Figure 7 shows an increase in rubber fracture for the less rough sample, showing some sensitivity to the crack opening mode. Yet, the rougher sample shows no mode dependency.

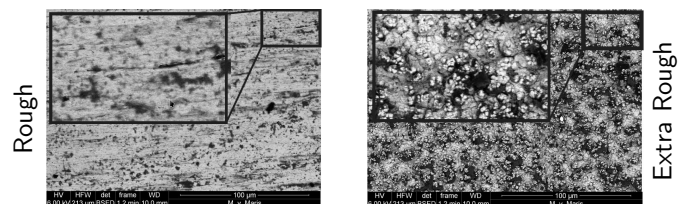


Figure 7: The new metal surfaces for both roughnesses, for a 0° peel test, i.e. crack shearing mode.

Conclusions

- In-situ ESEM imaging revealed a complex mechanism, which is the dominating dissipation mechanism
- The roughness initiates and controls the fibrillation process
- The fibrils and large surface roughness cause these interfaces to be insensitive to the crack opening mode, due to the “local” mode-mixity in the roughness morphology and the orientational freedom of the fibrils
- Future designs of stretchable electronic devices should aim to initiate the fibril process, with an artificial “tailored” roughness